JP 58-42290

409 withdrawn

AN 1983:523789 CAPLUS
DN 99:123789
TI Flexible printed circuit boards
PA Hitachi Chemical Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 3 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
IC H05K001-03; H05K001-02
CC 38-3 (Plastics Fabrication and Uses)
Section cross-reference(s): 76
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI JP 58042290	A2	19830311	JP 1981-141489	19810907

AB Thin, mech. strong circuit boards having excellent heat and moisture resistance comprise fluoropolymer films pretreated for good adhesion and coated on both sides with heat-resistant polymers contg. heterocyclic groups or precursors-thereof, then heat treated and laminated with metal foil. Thus, a 50-.mu. PTFE [9002-84-0] film was pretreated in aq. alkali, then dipped in a 20% soln. of HI-400 [25119-99-7] (polyimide) in N-methyl-2-pyrrolidone, dried 30 min at 150.degree., and baked 30 min at 250.degree. to obtain a flexible board 75-.mu. thick, which was laminated with Cu foil using a mixt. of EP-4000 **[11121-15-6]** and Epikote 828 [25068-38-6] epoxy resins and B-002 [39387-07-0] (heterocyclic polyamine). The resulting board showed no sign of damage after exposure to solder at 260.degree. for 30 s.

ST flexible circuit board PTFE polyimide; heat moisture resistant circuit board

IT Epoxy resins, uses and miscellaneous
RL: TEM (Technical or engineered material use); USES (Uses)
(adhesives, for bonding copper foil to polyimide surfaces)

IT Fluoropolymers
RL: USES (Uses)
(films, contg. heterocyclic polymer reinforcing coatings, for flexible circuit boards)

IT Plastics, film
RL: USES (Uses)
(fluoropolymers contg. heterocyclic polymer reinforcing coatings, for flexible printed circuit boards)

IT Coating materials
(heterocyclic polymers, for reinforcing of fluoropolymer films, for flexible printed circuit boards)

IT Heat-resistant materials
(polyimide-coated PTFE films, for flexible printed circuit boards)

IT Electric circuits
(printed, boards, flexible, fluoropolymer films coated with heterocyclic polymers, heat- and moisture-resistant)

IT **11121-15-6** 25068-38-6
RL: TEM (Technical or engineered material use); USES (Uses)
(adhesives, for bonding copper foil to polyimide surfaces)

IT 25119-99-7
RL: USES (Uses)
(coatings, reinforcing, on fluoropolymer films, for flexible printed circuit boards)

IT 39387-07-0
RL: MOA (Modifier or additive use); USES (Uses)
(crosslinking agents, for epoxy adhesives bonding copper foil to polyimide surfaces)

RN 11121-15-6 REGISTRY
CN Poly[oxy(methyl-1,2-ethanediyl)],
.alpha.,.alpha.'-[(1-methylethylidene)di-
4,1-phenylene]bis[.omega.-(oxiranylmethoxy)-, homopolymer (9CI) (CA
INDEX
NAME)
OTHER NAMES:
CN Adeka EP 4000
CN Adeka Resin EP 4000
CN ADK 4000
CN EP 4000
CN Epiclon 717
CN Gurishieru BPP 350
CN **Rikaresin BPO 20E**
DR 54667-37-7, 60267-15-4, 63278-42-2, 39354-76-2
MF ((C3 H6 O)n (C3 H6 O)n C21 H24 O4)x
CI PMS, COM
PCT Epoxy resin, Polyether
LC STN Files: CA, CAPLUS, CHEMLIST, IFICDB, IFIPAT, IFIUDB, USPATFULL

CM 1

CRN 55236-42-5
CMF (C3 H6 O)n (C3 H6 O)n C21 H24 O4
CCI IDS, PMS

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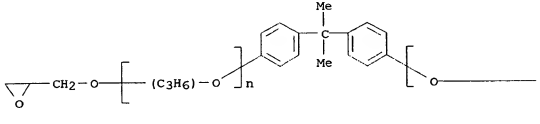

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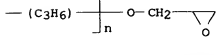

93 REFERENCES IN FILE CA (1967 TO DATE)
23 REFERENCES TO NON-SPECIFIC DERIVATIVES IN FILE CA
93 REFERENCES IN FILE CAPLUS (1967 TO DATE)